



## A Surge-protected, 28 V Tolerant Power Splitter in WLCSP

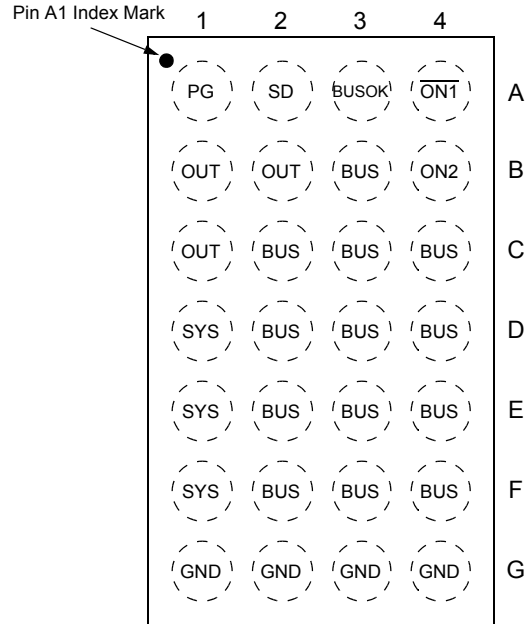
### General Description

The SLG59H1302C is a 130-V surge-protected, 28-V tolerant power splitter with two high-current switches and an 0.1 A capable LDO in 28-ball WLCSP. With independent control for each channel, the SLG59H1302C contains a 6 A capable, 12 mΩ nFET switch for the BUS-to-OUT path and a reverse-blocking 6 A capable, 24 mΩ nFET switch for the BUS-to-SYS path. An internal, “always ON” LDO is 0.1 A capable and can be used to supply power to downstream devices when the BUS terminal voltage is higher than 2.7 V. When the SYS terminal turns on, the IC’s push-pull PG output becomes asserted. The SLG59H1302C is fully specified over the industrial -40°C to 85°C temperature range.

### Features

- 130 V-tolerant TVS (IEC61000-4-5)
- BUS-to-OUT nFET: 12 mΩ/6 A, 28 V tolerant
- BUS-to-SYS nFET: 24 mΩ/6 A B2B RB
- Always ON, BUS LDO: ±10% tol, 0.1 A capable
- BUS UVLO & OVLO Protection
  - OVP Response Time: 200 ns
- Push-pull PG (Power Good) Output
- Thermal Shutdown Protection
- Active-HIGH IC Shutdown Input
- Active-LOW  $\overline{\text{ON1}}$  Input (BUS-to-OUT)
- Active-HIGH ON2 Input (BUS-to-SYS)
- 28-ball CSP, 2.98 x 1.69 x 0.44 mm, 0.4 mm pitch
- Pb-Free / Halogen-Free / RoHS Compliant Packaging

### Pin Configuration

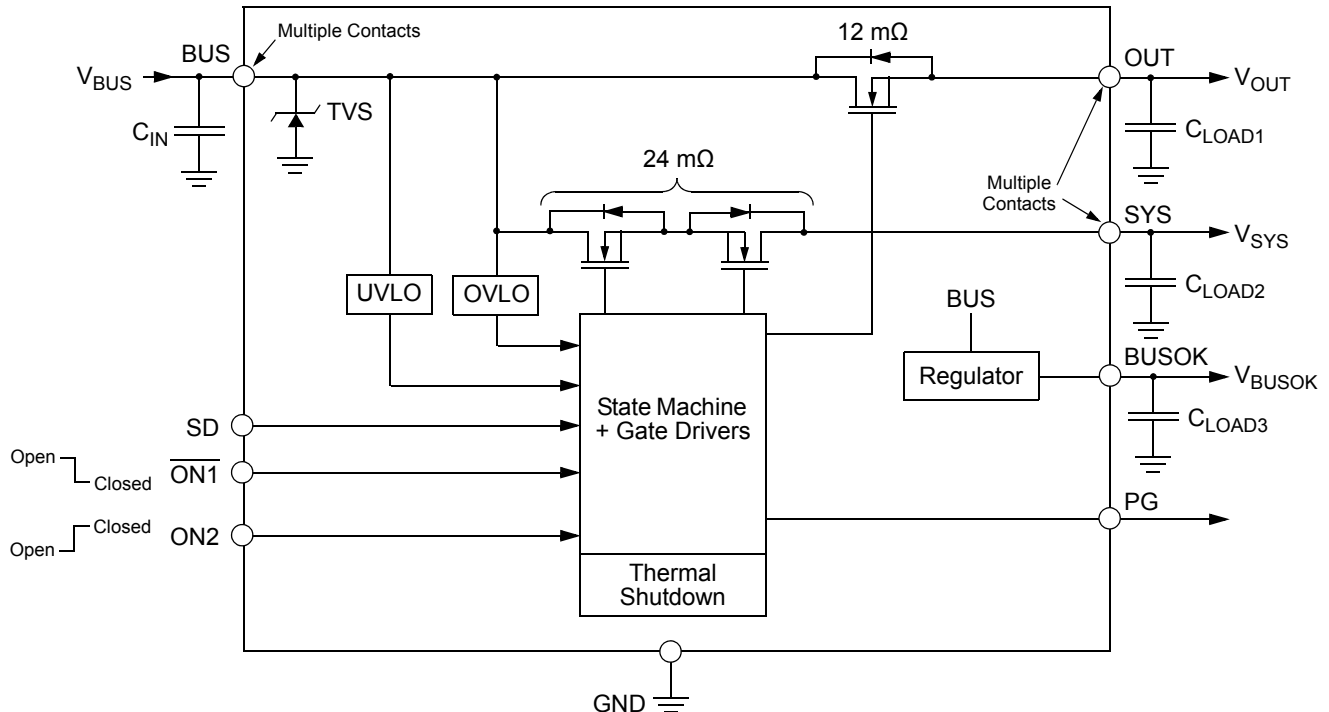


**(Laser Marking View)**  
2.98 x 1.69 x 0.44 mm, 0.4 mm pitch

### Applications

- Wearable Devices
- Tablet PCs and Smartphones

### Block Diagram





### Pin Description

Pin Name	Pin #	Type	Pin Description
BUS	B3, C2, C3, C4, D2, D3, D4, E2, E3, E4, F2, F3, F4	Input	IC power supply and power switch input (13 contacts)
OUT	B1, B2, C1	Output	Power switch output to Load (3 contacts)
SYS	D1, E1, F1	Output	Power switch output to VBAT (3 contacts)
BUSOK	A3	Output	Always ON fixed output voltage from internal LDO
ON2	B4	Digital Input	BUS-to-SYS Switch Enable; Asserted active high digital input; 1 M $\Omega$ pull-down
$\overline{\text{ON1}}$	A4	Digital Input	BUS-to-OUT Switch Enable; Asserted active low digital input; 1 M $\Omega$ pull-down
SD	A2	Digital Input	IC shutdown; asserted active high; 1 M $\Omega$ pull-down
PG	A1	Digital Output	Asserted active-high push-pull output.
GND	G1, G2, G3, G4	GND	Analog GND (4 contacts)

### Ordering Information

Part Number	Type	Production Flow
SLG59H1302C	WLCSP 28L	Industrial, -40 °C to 85 °C
SLG59H1302CTR	WLCSP 28L (Tape and Reel)	Industrial, -40 °C to 85 °C



## Absolute Maximum Ratings

Parameter	Description	Conditions	Min.	Typ.	Max.	Unit
V <sub>BUS</sub> to GND	Power Switch Input Voltage to Ground	Continuous	-0.3	--	28	V
V <sub>SYS</sub> to GND	Power Switch Output Voltage to Ground	Continuous	-0.3	--	6	V
		Max pulse width 0.1s	-0.3	--	7	V
V <sub>OUT</sub> to GND	Power Switch Output Voltage to GND	$\overline{\text{ON1}} = \text{LOW}$	-0.3	--	V <sub>BUS</sub>	V
ESD <sub>HBM</sub>	ESD Protection	Human Body Model, All pins	2000	--	--	V
ESD <sub>CDM</sub>	ESD Protection	Charged Device Model, All pins	1000	--	--	V
ESD <sub>SURGE</sub>	ESD Protection	VBUS Surge Protection, IEC 61000-4-5	+130	--	--	V
OUT IDS	Maximum Current from BUS to OUT	Continuous	-0.3	--	6	A
		Max pulse width 10 ms	-0.3	--	7	A
SYS IDS	Maximum Current from BUS to SYS	Continuous	-0.3	--	6	A
		Max pulse width 10 ms	-0.3	--	7	A
BUSOK IDS	Maximum Current from BUS to BUSOK	Continuous	-0.3	--	100	mA
$\theta_{JA}$	Package Thermal Resistance, Junction-to-Ambient	2.98 x 1.69 mm 28L WLCSP; Determined using a 1 in <sup>2</sup> , 1 oz. copper pad under each BUS, SYS, and OUT terminal and FR4 pcb material.	--	45	--	°C/W

Note: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

## Recommended Operating Conditions

T<sub>A</sub> = -40 °C to 85 °C (unless otherwise stated)

Parameter	Description	Min.	Typ.	Max.	Unit
<b>Basic Operation</b>					
V <sub>BUS</sub>	IC Power supply and power switch input voltage	2.7	--	13.2	V
C <sub>IN</sub> /C <sub>OUT</sub>	Input and Output Capacitance	--	1	--	μF
C <sub>SYS</sub>	SYS Capacitance	47	--	--	μF
C <sub>BUSOK</sub>	Output Capacitance	--	4.7	--	μF
T <sub>A</sub>	Operating Temperature	-40	--	85	°C

## Electrical Characteristics

T<sub>A</sub> = -40 °C to 85 °C (unless otherwise stated)

Parameter	Description	Conditions	Min.	Typ.	Max.	Unit
<b>Basic Operation (V<sub>BUS</sub> = 12 V, no load)</b>						
I <sub>Q</sub>	Input Quiescent Current	V <sub>BUS</sub> = 4 V, $\overline{\text{ON1}} = \text{LOW}$ , No Load	--	180	--	μA



## Electrical Characteristics (continued)

T<sub>A</sub> = -40 °C to 85 °C (unless otherwise stated)

Parameter	Description	Conditions	Min.	Typ.	Max.	Unit
I <sub>IN_Q</sub>	Input Supply Current when V <sub>OUT_OVLO</sub> or V <sub>SYS_OVLO</sub> threshold is reached	V <sub>BUS</sub> = 15 V, $\overline{ON1}$ = LOW, ON2 = HIGH, BUSOK = 1 kΩ Load	--	4.2	--	mA
I <sub>SD</sub>	Shutdown Current	V <sub>BUS</sub> = 12 V	--	1	2	μA
V <sub>BUS_UVLO</sub>	Under Voltage Trip Level	T <sub>A</sub> = 0 °C to 85 °C	2.3	2.4	2.7	V
t <sub>BUS_START</sub>	Soft-Start Time	See timing diagram	--	30	--	ms
THERM <sub>ON</sub>	Thermal Shutdown Turn-on Temperature		--	145	--	°C
THERM <sub>HYS</sub>	Thermal Shutdown Hysteresis		--	20	--	°C
<b>BUS To OUT Switch</b>						
V <sub>OUT_OVLO</sub>	Over Voltage Trip Level	V <sub>BUS</sub> Rising	13.2	13.9	14.5	V
V <sub>OUT_HYS</sub>	V <sub>OUT</sub> Hysteresis		--	350	--	mV
RDS <sub>ON</sub>	ON Resistance	V <sub>BUS</sub> = 12 V, I <sub>OUT</sub> = 0.1 A, T <sub>A</sub> = 25 °C	--	12	14	mΩ
		V <sub>BUS</sub> = 12 V, I <sub>OUT</sub> = 0.1 A, T <sub>A</sub> = 85 °C	--	16	18	mΩ
t <sub>DEB_OUT</sub>	Debounce Time	$\overline{ON1}$ = 0 V; V <sub>BUS</sub> > V <sub>BUS_UVLO</sub> to 0.1 x V <sub>OUT</sub> ; See timing diagram	--	15	--	ms
t <sub>ON_OUT</sub>	Switch Turn-On Time	R <sub>LOAD</sub> = 100 Ω, C <sub>LOAD</sub> = 4.7 μF; V <sub>OUT</sub> from 0.1 x V <sub>BUS</sub> to 0.9 x V <sub>BUS</sub>	--	2.5	--	ms
t <sub>OVP_OUT</sub> <sup>1</sup>	Overvoltage Protection Time	I <sub>LOAD</sub> = 100 mA, no C <sub>LOAD</sub> ; V <sub>BUS</sub> step up over V <sub>OUT_OVLO</sub> to V <sub>OUT</sub> start separate from V <sub>BUS</sub>	--	200	--	ns
t <sub>OFF_OUT</sub>	Switch Turn-Off Time	50 % $\overline{ON1}$ ↑ to 0.9 x V <sub>OUT</sub> ; V <sub>BUS</sub> = 12 V R <sub>LOAD</sub> = 100 Ω, no C <sub>LOAD</sub>	--	5	--	μs
<b>BUS To SYS Switch</b>						
V <sub>SYS_OVLO</sub>	Over Voltage Trip Level	V <sub>BUS</sub> Rising	4.9	5.25	5.5	V
V <sub>SYS_HYS</sub>	V <sub>SYS</sub> Hysteresis		--	110	--	mV
RDS <sub>ON</sub>	ON Resistance	V <sub>BUS</sub> = 5 V, I <sub>SYS</sub> = 0.1 A, T <sub>A</sub> = 25 °C	--	24	29.6	mΩ
		V <sub>BUS</sub> = 5 V, I <sub>SYS</sub> = 0.1 A, T <sub>A</sub> = 85 °C	--	30	38	mΩ
I <sub>RCB</sub>	Reverse Current	V <sub>SYS</sub> = 4.4 V, measured from V <sub>BUS</sub> to GND <sup>1</sup>	--	10	--	nA
t <sub>DEB_SYS</sub>	Debounce Time	See timing diagram	--	15	--	ms
t <sub>SYS_START</sub>	Soft-Start Time	See timing diagram	--	30	--	ms
t <sub>ON_SYS</sub>	Switch Turn-On Time	R <sub>LOAD</sub> = 100 Ω, C <sub>LOAD</sub> = 4.7 μF; V <sub>SYS</sub> from 0.1 x V <sub>BUS</sub> to 0.9 x V <sub>BUS</sub>	--	3.0	--	ms
t <sub>OVP_SYS</sub> <sup>1</sup>	Overvoltage Protection Time	I <sub>LOAD</sub> = 100 mA, no C <sub>LOAD</sub> ; V <sub>BUS</sub> step up over V <sub>SYS_OVLO</sub> to V <sub>SYS</sub> start separate from V <sub>BUS</sub>	--	200	--	ns
t <sub>OFF_SYS</sub>	Switch Turn-Off Time	50 % ON2 ↓ to 0.9 x V <sub>SYS</sub> ; V <sub>BUS</sub> = 5 V; R <sub>LOAD</sub> = 100 Ω, no C <sub>LOAD</sub>	--	5	--	μs



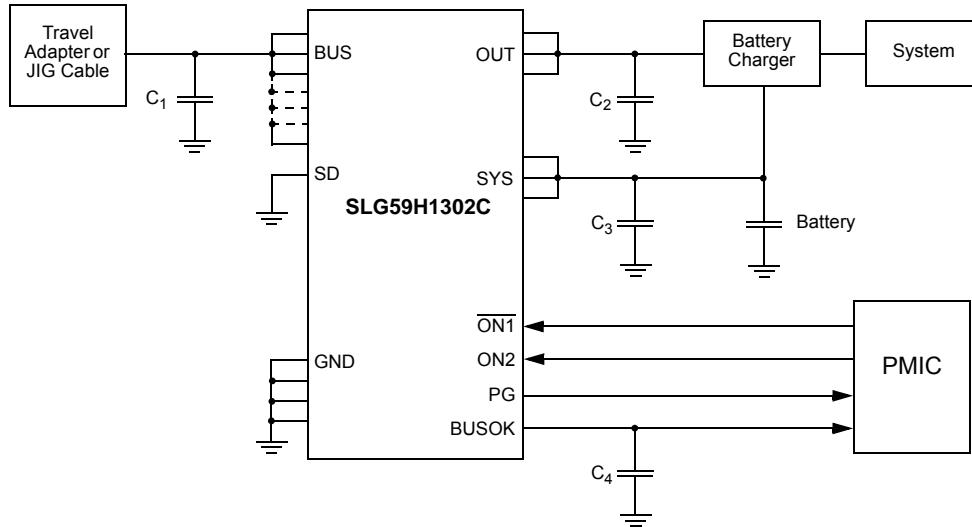
### Electrical Characteristics (continued)

T<sub>A</sub> = -40 °C to 85 °C (unless otherwise stated)

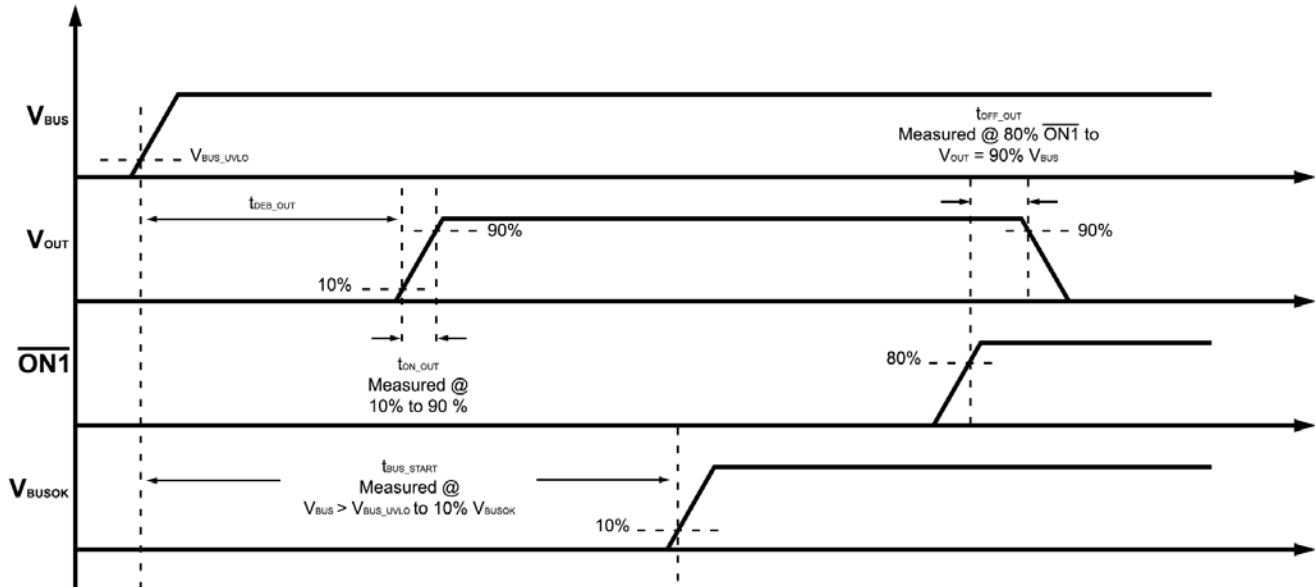
Parameter	Description	Conditions	Min.	Typ.	Max.	Unit
<b>BUSOK</b>						
V <sub>BUSOK</sub>	BUSOK Output voltage	V <sub>BUS</sub> = 5 V, no load	3.8	4.0	4.4	V
		V <sub>BUS</sub> = 12 V, no load	3.8	4.0	4.4	V
		V <sub>BUS</sub> = 5 V; BUSOK IDS = 100 mA	3.6	3.8	4.1	V
		V <sub>BUS</sub> = 12 V; BUSOK IDS = 100 mA	3.6	3.8	4.1	V
<b>Digital Signals</b>						
V <sub>OH_PG</sub>	PG Output HIGH Voltage	ON2 = Low to High, V <sub>BUS</sub> = 3.4 V to 5 V	--	1.8	--	V
V <sub>OL_PG</sub>	PG Output LOW Voltage	ON2 = High to Low, V <sub>BUS</sub> = 3.4 V to 5 V	--	--	0.3	V
R <sub>PD(ONx, SD)</sub>	Internal Pull-Down Resistor at ON1, ON2, and SD		--	1	--	MΩ
V <sub>IH(ONx, SD)</sub>	Logic Enable HIGH Voltage		0.9	--	--	V
V <sub>IL(ONx, SD)</sub>	Logic Enable LOW Voltage		--	--	0.3	V
I <sub>LKG(BUSOK)</sub>	BUSOK Leakage Current		--	--	1	μA
I <sub>LKG(ONx, SD)</sub>	SD, ONx Leakage current	V <sub>BUS</sub> = 12 V	--	--	5	μA
Notes:						
1. Based on bench measurement only.						



## Typical Application Diagram

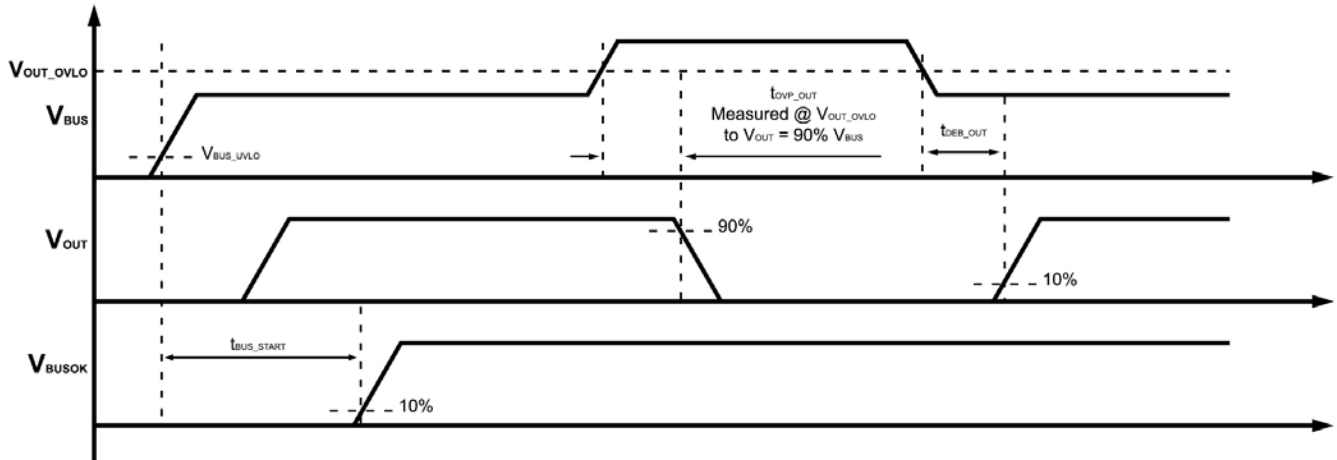


## Timing for BUS to OUT Power Up/Down and Normal Operation

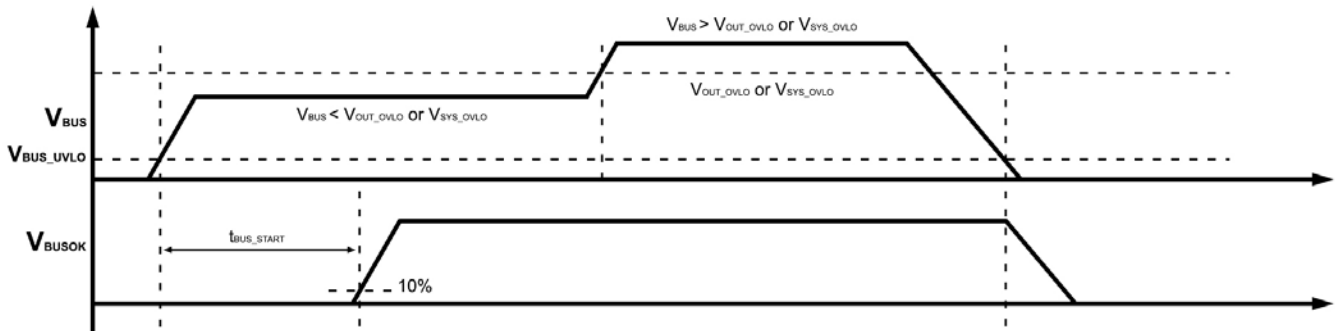




Timing for BUS to OUT OVLO Operation ( $\overline{ON1} = \text{LOW}$ )

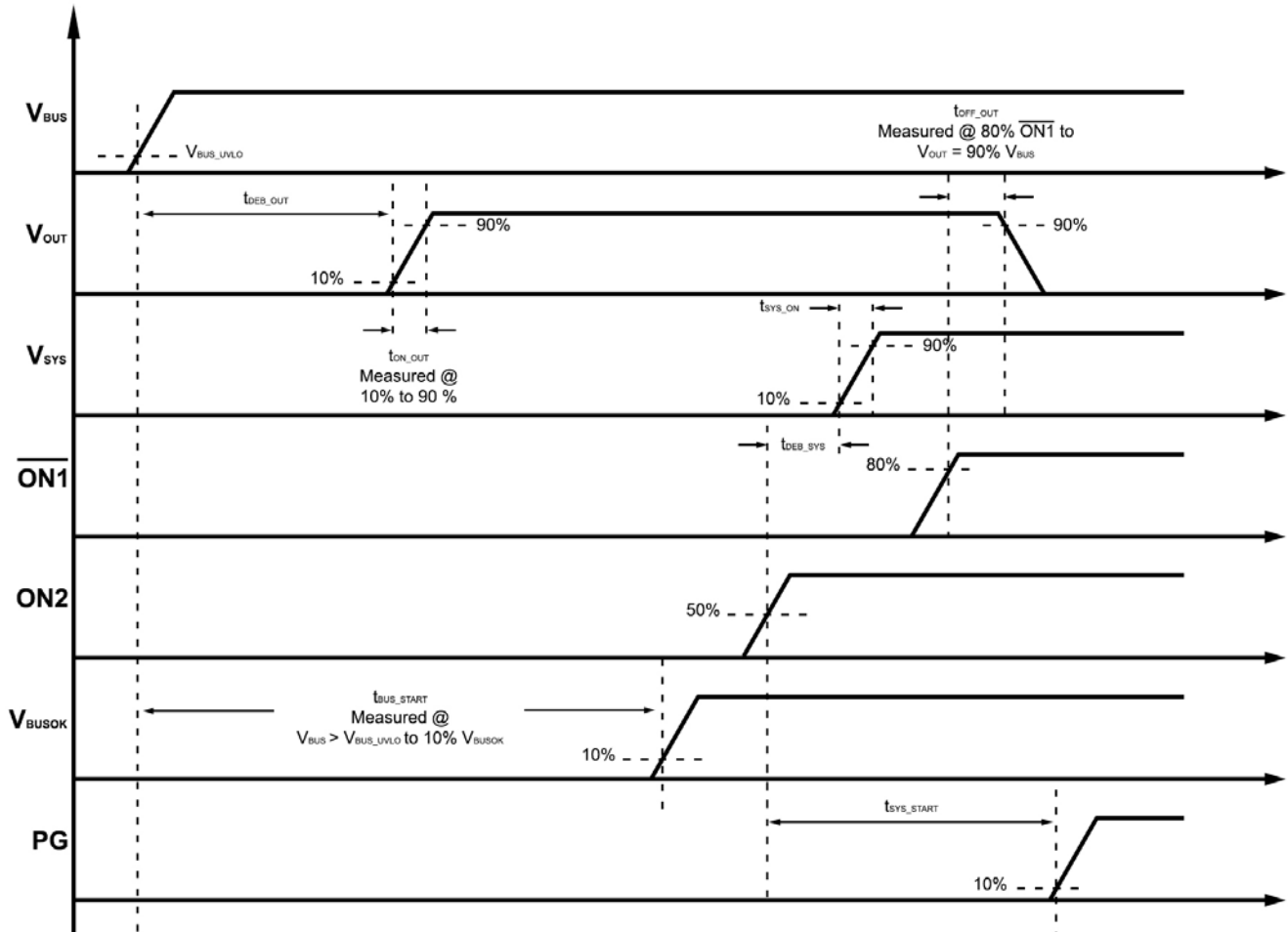


“Always ON” based BUSOK Operation ( $\overline{ON1} = X$ ,  $ON2 = X$ ,  $SD = \text{LOW}$ )





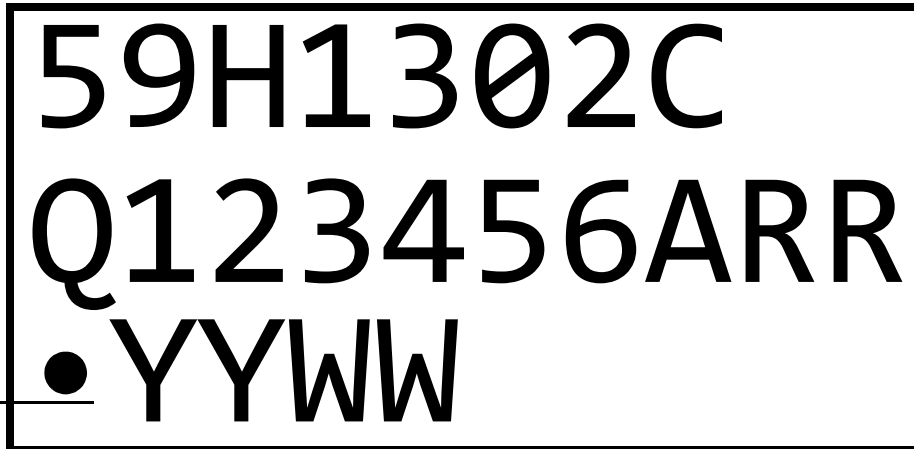
### Timing for Overall ON/OFF Operation (SD = LOW)







Package Top Marking System Definition



Pin 1 Identifier

59H1302C - Part ID Field

Q123456 - Assembly Lot Traceability Code Field<sup>1</sup>

A - Assembly Site Code Field<sup>2</sup>

RR - Part Revision Code Field<sup>2</sup>

YY - Year Code Field<sup>1</sup>

WW - Week Code Field<sup>1</sup>

Note 1: Each character in code field can be alphanumeric A-Z and 0-9

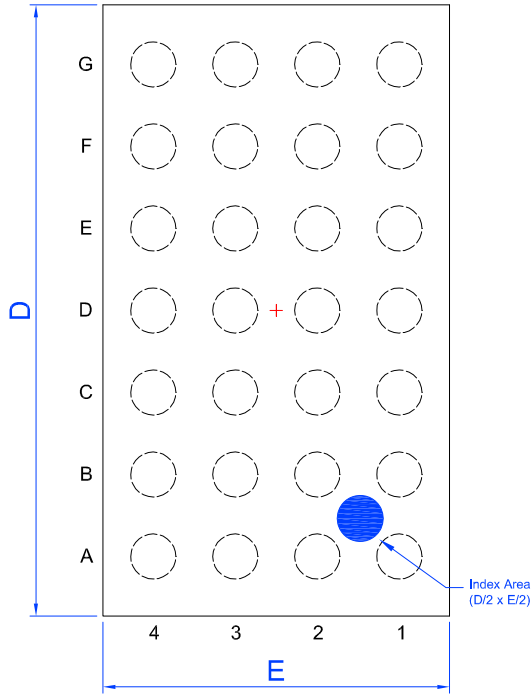
Note 2: Character in code field can be alphabetic A-Z



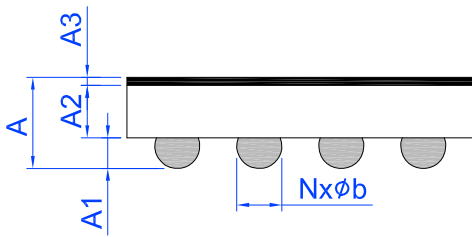
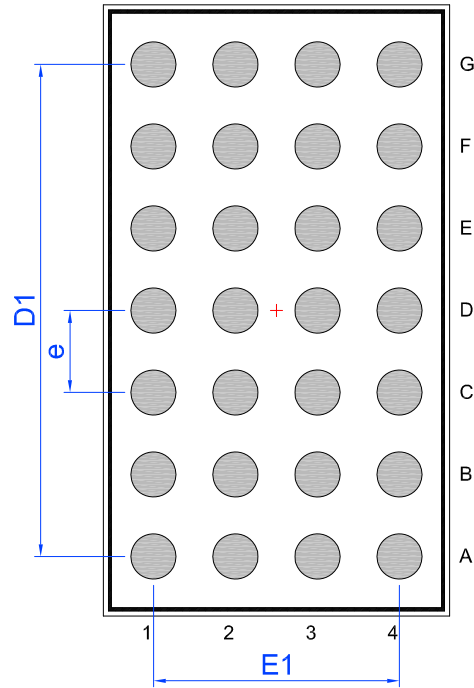
**Package Drawing and Dimensions**

28 Lead WLCSP Package

**Laser Marking View**



**Bump View**



**SIDE View**

TERMINALS ASSIGNMENTS				
G	GND	GND	GND	GND
F	SYS	BUS	BUS	BUS
E	SYS	BUS	BUS	BUS
D	SYS	BUS	BUS	BUS
C	OUT	BUS	BUS	BUS
B	OUT	OUT	BUS	ON1
A	SD	PG	BUSOK	ON2
	1	2	3	4

Unit: mm

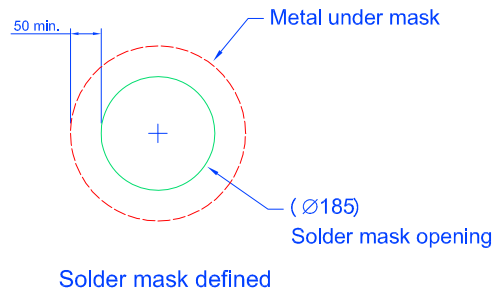
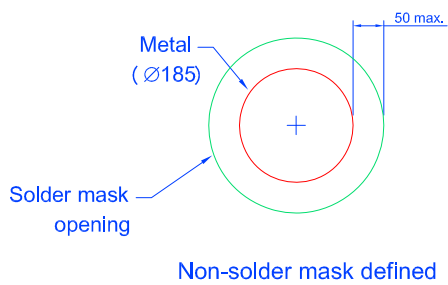
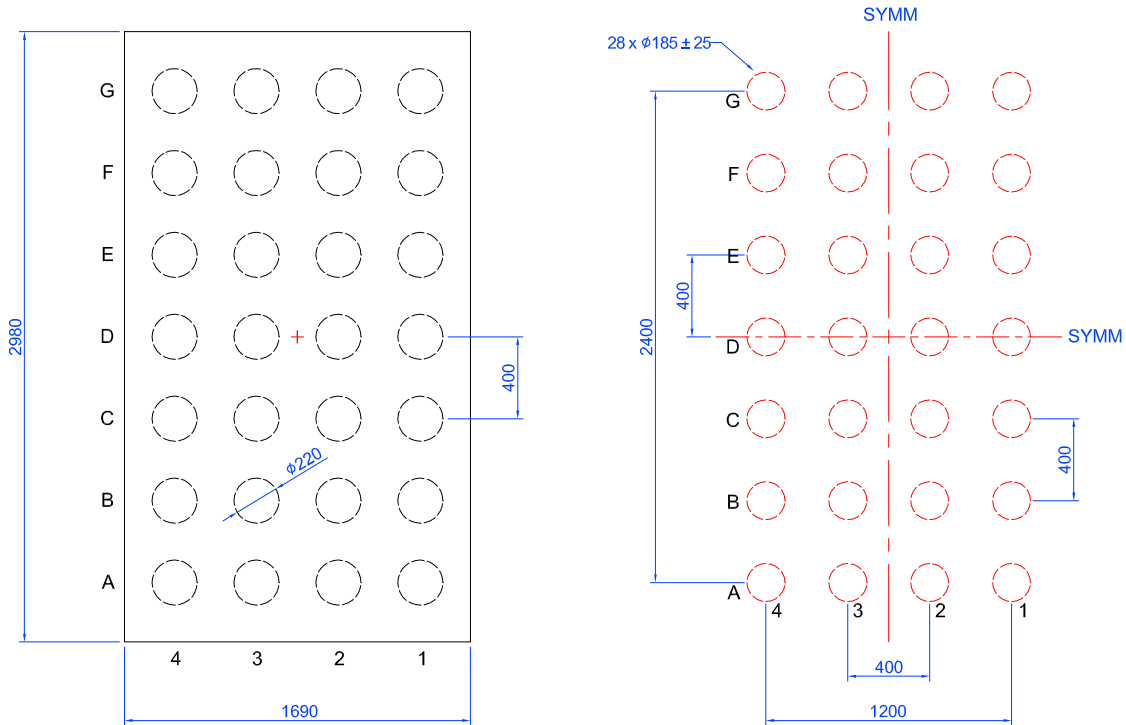
Symbol	Min	Nom.	Max	Symbol	Min	Nom.	Max
A	0.380	-	0.500	D	2.95	2.98	3.01
A1	0.125	0.150	0.175	E	1.66	1.69	1.72
A2	0.240	0.265	0.290	D1	2.40 BSC		
A3	0.015	0.025	0.035	E1	1.20 BSC		
b	0.195	0.220	0.245	e	0.40 BSC		
N	28 (Bump)						



## SLG59H1302C 28-pin WLCSP PCB Landing Pattern

○ Exposed Bump  
(Laser marking view)

⊕ Recommended Land Pattern  
(Laser marking view)



Solder mask detail (not to scale)

Unit: um

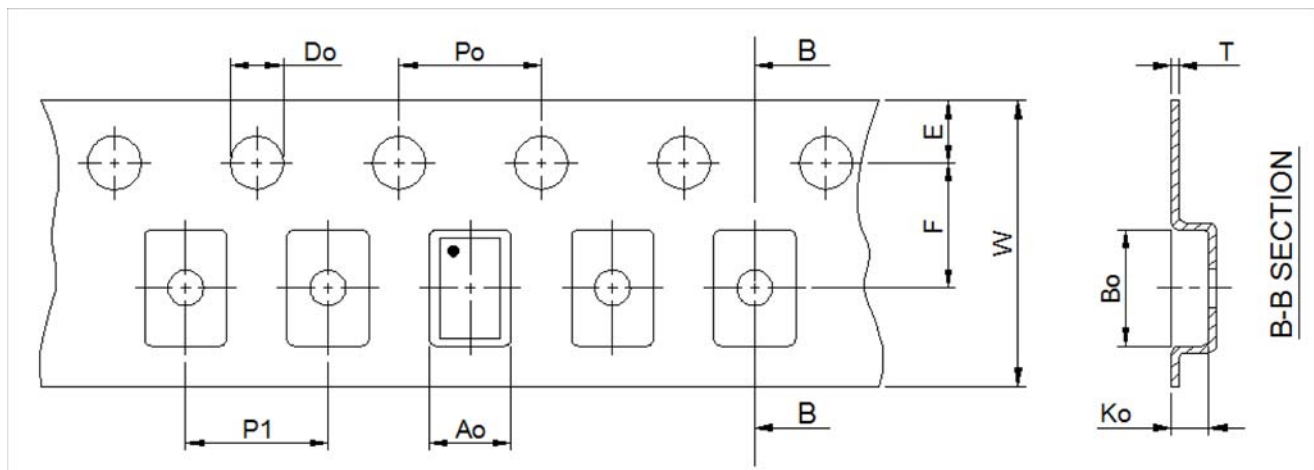


**Tape and Reel Specifications**

Package Type	# of Pins	Nominal Package Size [mm]	Max Units		Reel & Hub Size [mm]	Leader (min)		Trailer (min)		Tape Width [mm]	Part Pitch [mm]
			per Reel	per Box		Pockets	Length [mm]	Pockets	Length [mm]		
WLCSP 28L 2.98x1.69 mm 0.4P Green	28	2.98 x 1.69 x 0.44	3000	3000	178/60	100	400	100	400	8	4

**Carrier Tape Drawing and Dimensions**

Package Type	Pocket BTM Length	Pocket BTM Width	Pocket Depth	Index Hole Pitch	Pocket Pitch	Index Hole Diameter	Index Hole to Tape Edge	Index Hole to Pocket Center	Tape Width	Tape Thickness
	A0	B0	K0	P0	P1	D0	E	F	W	T
WLCSP 28L 2.98x1.69 mm 0.4P Green	1.85	3.25	0.7	4	4	1.55	1.75	3.5	8	0.25



Refer to EIA-481 specification

**Recommended Reflow Soldering Profile**

Please see IPC/JEDEC J-STD-020: latest revision for reflow profile based on package volume of 2.09 mm<sup>3</sup> (nominal). More information can be found at [www.jedec.org](http://www.jedec.org).



**Revision History**

Date	Version	Change
6/14/2017	1.00	Production Release